| PCN Number: | | | 20230306001.1 | | | | PCN Date: | | Marc | March 08, 2023 | |
|--|--------|--------------|---------------|---------|--------------------|----------|-----------|---------------------|---------------------------|------------------|--|
| Title: Datasheet for | | | | | | | | | | | |
| Customer Contact: PCN | | | | Manager | | | | Dept: | | Quality Services | |
| | | | | June | lune 8, 2023 | | | | | | |
| Change Type: | | | | | | | | | | | |
| Assembly Site | | | | | | Design | | | Wafer Bump Site | | |
| Assembly Process | | | | X | Data Sheet | ta Sheet | | | Bump Material | | |
| Assembly Materials | | | | | Part number change | | | Wafer | Wafer Bump Process | | |
| Mechanical Specification | | | | | Test Site | | | Wafer | Wafer Fab Site | | |
| Packing/Shipping/Labeling | | | ıg | | Test Process | | | Wafer Fab Materials | | | |
| | | | | | | | | Wafer | Fab Process | | |
| Notification Details | | | | | | | | | | | |
| Desc | cripti | on of Change | e: | | | | | | | | |
| Texas Instruments Incorporated is announcing an information only notification. | | | | | | | | | | | |
| The product datasheet(s) is being updated as summarized below. | | | | | | | | | | | |
| ₹/i ŢEXAS OPA277, OPA2277, OPA4277 | | | | | | | | | | | |
| Instruments | | | | | | SBOS0 | 79C - | | 9 - REVISED FEBRUARY 2023 | | |

| Changes from Revision B (April 2015) to Revision C (February 2023) | Page |
|---|------|
| Updated the numbering format for tables, figures, and cross-references throughout the document | 1 |
| Changed Applications bullets to include links | |
| Deleted text regarding identical specification for the single, dual, and quad versions | |
| Changed Offset Trim pin type from "Input" to "—" | 3 |
| Changed "DFN" to "DRM (VSON)" in OPA2277 Pin Functions table | 3 |
| Added table note for 10-mA current limit on input pins in Absolute Maximum Ratings | |
| Deleted operating temperature from Absolute Maximum Ratings | |
| Deleted lead temperature from Absolute Maximum Ratings | |
| Changed Thermal Information values for OPA2277 and OPA4277 SOIC packages | |
| Added test conditions to Electrical Characteristics header | 8 |
| Changed format of Electrical Characteristcs for readability | |
| Changed input offset voltage vs. time to long-term drift in Electrical Characteristics | 8 |
| Changed input bias current test condition to separate over temperature specification | 8 |
| Deleted redundant row in open-loop gain parameter | |
| Changed C _{LOAD} to C _L for consistency | |
| Changed Figure 6-14, Change in Input Bias Current vs Common-Mode Voltage, to correct typo in note | |
| Changed "DFN package" to "DRM package (8-pin VSON)" | |
| Changed "DFN package" to "DRM Package" and added "8-Pin VSON" | |
| Changed Development Support section to show updated links and resources | |

The datasheet number will be changing.

| Device Family | Change From: | Change To: |
|---------------|--------------|------------|
| OPAx277 | SBOS079B | SBOS079C |

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/OPA2277

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

Product Affected:

| OPA2277AIDRMT | OPA2277UA/2K5 | OPA277PA | OPA277UAG4 |
|-----------------|-----------------|----------------|-----------------|
| OPA2277AIDRMTG4 | OPA2277UA/2K5E4 | OPA277PAG4 | OPA277UG4 |
| OPA2277P | OPA2277UAE4 | OPA277U | OPA4277PA |
| OPA2277PA | OPA2277UAG4 | OPA277U/2K5 | OPA4277UA |
| OPA2277PAG4 | OPA2277UG4 | OPA277U/2K5G4 | OPA4277UA/2K5 |
| OPA2277U | OPA277AIDRMR | OPA277UA | OPA4277UA/2K5E4 |
| OPA2277U/2K5 | OPA277AIDRMT | OPA277UA/2K5 | OPA4277UAE4 |
| OPA2277U/2K5G4 | OPA277AIDRMTG4 | OPA277UA/2K5E4 | OPA4277UAG4 |
| OPA2277UA | OPA277P | OPA277UAE4 | |

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

| Location | E-Mail | | | |
|-------------|--------------------------------|--|--|--|
| WW PCN Team | PCN www admin_team@list.ti.com | | | |

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.